

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	128	(bga or ball near grid near array) and (underfill\$4) and (overmold\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/10 13:31
S39	65	(underfill\$4 or under-fill\$4) near10 (barrier or dam or seal or wall or ridge) and ((reduct\$3 or eliminat\$3 or decrease\$3) near3 (gap or void or voided or air or bubble) or void-free)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/03 11:22
S37	76	(underfill\$4 or under-fill\$4) near10 (simultaneous\$3 or concurrent\$3) near10 (overmold\$4 or mold\$4 or encapsula\$4)	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/03 11:14
S36	43	(underfill\$4 or under-fill\$4) near6 (separat\$4 or isolat\$4) near6 (overmold\$4 or mold\$4 or encapsula\$4)	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/03 10:47
S34	43	(underfill\$4 or under-fill\$4) near6 (separat\$4 or isolat\$4) near6 (overmold\$4 or mold\$4 or encapsula\$4)	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/03 10:08
S35	1	"6122187".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/02 16:26
S31	68	(underfill\$4 or under-fill\$4) near4 (barrier or dam or seal or blocking or blocker or sealing or dammed) near10 (flow\$3 or molding or encapsulant or molded or mold or encapsulation or encapsulating)	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/02 13:43
S33	29	("4081825" "4628406" "4825284" "4873615" "5081067" "5113241" "5201866" "5218234" "5239200" "5249101" "5289346" "5291064" "5371404" "5379191" "5396403" "5432675" "5438216" "5450283" "5468995" "5477082" "5488254" "5489801" "5610442" "5656857" "5672548" "5734201" "5801836" "5959362" "5969426").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/02 13:33
S32	1	("2002/0109218").URPN.	USPAT	OR	ON	2006/03/02 13:28
S29	520	(underfill\$4 or under-fill\$4) near4 (barrier or dam or seal or blocking or blocker or sealing or dammed)	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/02 13:15

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S28	3	("6228681" "6245595" "6265776"). PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/02 13:14
S27	99	(wall or stencil or barrier or ridge or raised or standoff or socket or recess\$) near4 (around or surround\$4 or circumscribing) near4 (die or chip or ic) same (encapsula\$5 or mold or molding or underfill\$4) and (chip or die or ic or integrated adj circuit) near3 (package or packaging or housing or packaged)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/02 12:54
S26	247	(underfill or encapsulant or encapsulation or encapsulating or molding or mold) near2 (barrier or dam or wall or ridge) near10 (chip or die or integrated adj circuit) and (chip or die or integrated adj circuit) near3 (package or packaging or housing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/02 12:36
S25	22	"6025648".pn. "6324069".pn. "5854507".pn. "5883426".pn. "6563712".pn. "6580169".pn. "6121682".pn. "6757967".pn. "5583378".pn. "6048656".pn. "5841194".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/02 11:06